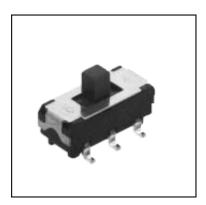


3.5(H)mm, 2.0mm-travel Type SSSS2 Series

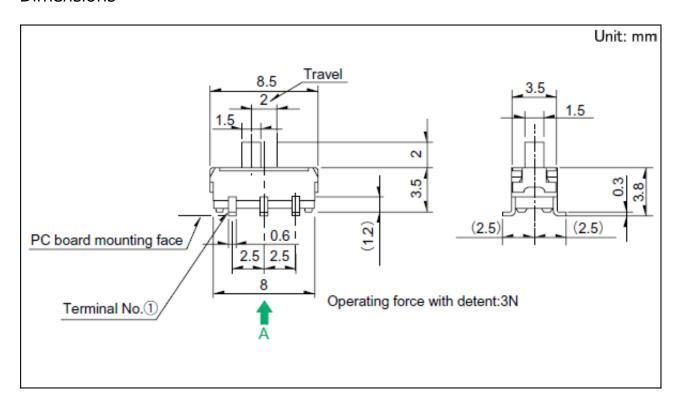
| Part number | | | SSSS213202 |
|---------------------------------------|--|---------------------|--------------------------------------|
| Travel | | | 2mm |
| Actuator directions | | | Vertical |
| Actuator length | | | 2mm |
| Poles | | | 1 |
| Positions | | | 2 |
| Operating force | | | Refer to the dimensions. |
| Changeover timing | | | Non shorting |
| Soldering | | | Reflow |
| Operating temperature range | | | -40℃ to +85℃ |
| Rating (max.)/(min.) (Resistive load) | | | 0.3A 6V DC/50μA 3V DC |
| Electrical performance | Contact resistance (Initial performance/After lifetime) | | 70m Ω max./130m Ω max. |
| | Insulation resistance | | 100MΩ min. 500V DC |
| | Voltage proof | | 500V AC for 1 minute |
| Mechanical performance | Terminal strength | | 3N for 1 minute |
| | Actuator strength | Operating direction | 20N |
| | | Pulling direction | 10N |
| Durability | Operating life without load | | 100 cycles 100m Ω max. |
| | Operating life with load (at max. rated load) | | 100 cycles 130m Ω max. |
| Environmental performance | Cold | | -20℃ 500h |

| Dry heat Damp heat | | 85℃ 500h |
|---------------------------|--------|-----------------------|
| | | 60℃, 90 to 95%RH 500h |
| Minimum order unit (pcs.) | Japan | 1,200 |
| | Export | 4,800 |

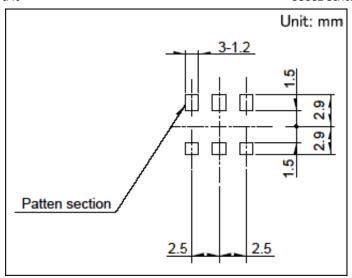
Photo



Dimensions

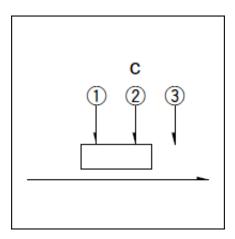


Land Dimensions



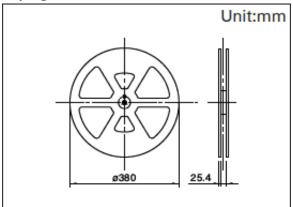
Viewed from direction A in the dimensions.

Circuit Diagram



Packing Specifications





| Number of packages (pcs.) | s 1 reel | 1,200 |
|---------------------------|-------------------------|-------|
| | 1 case / Japan | 2,400 |
| | 1 case / export packing | 4,800 |

Tape width (mm)

Export package measurements (mm)

428×413×172

Soldering Conditions

Example of Reflow Soldering Condition

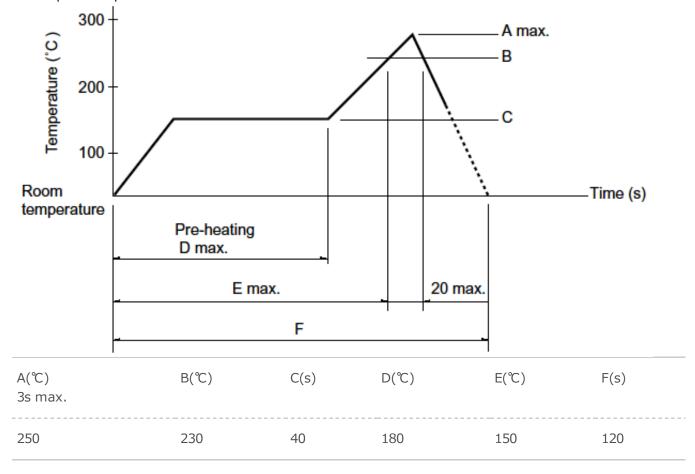
1. Heating method

Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



- (1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- (2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

| Soldering temperature | 350±10℃ |
|-----------------------|---------|
| Soldering time | 4s max. |

Notes are common to this series/models.

- 1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
- 2. Please place purchase orders per minimum order unit (integer).
- 3. Products other than those listed in the above chart are also available. Please contact us for details.